



Customer Information Notification

201901029I

Issue Date: 14-Mar-2019

Effective Date: 15-Mar-2019

Dear *Emma Tempest*,

Here's your personalized quality information concerning products Premier Farnell PLC purchased from NXP.

For detailed information we invite you to [view this notification online](#)



Change Category

- | | | | | |
|----------------------------------------------|---------------------------------------------|----------------------------------------------------|-----------------------------------------|--------------------------------------------------------------------|
| <input type="checkbox"/> Wafer Fab Process | <input type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Test Location | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab Materials | <input type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification | <input type="checkbox"/> Test Process | <input type="checkbox"/> Errata |
| <input type="checkbox"/> Wafer Fab Location | <input type="checkbox"/> Assembly Location | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Equipment | <input checked="" type="checkbox"/> Electrical spec./Test coverage |
| <input type="checkbox"/> Firmware | <input type="checkbox"/> Other | | | |

MC9S08PA4
Datasheet Update to
Revision 9

Description

NXP Semiconductors announces a data sheet update for the MC9S08PA4 to revision 9. The revision history included in the updated document provides a detailed description of the changes. Changes are summarized below.

1. Updated the S3IDD Typical values in Supply current characteristics.
2. Added the package drawing information of 20-pin TSSOP.

The MC9S08PA4 data sheet revision 9 is attached to this notice, and can be found at:
NXP PA4 datasheet link: <https://www.nxp.com/s08p>

Reason

The data sheet has been updated to correct errors and provide additional technical clarification on some device features.

Identification of Affected Products

Product identification does not change

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.

Data Sheet Revision

A new datasheet will be issued

Additional information

Affected products and sales history information: see attached file

Additional documents: [view online](#)



Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please [contact NXP "Global Quality Support Team"](#).

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name Jonson Chen
Position Application Engineer
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At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

Customer Focus, Passion to Win.

NXP Quality Management Team.

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